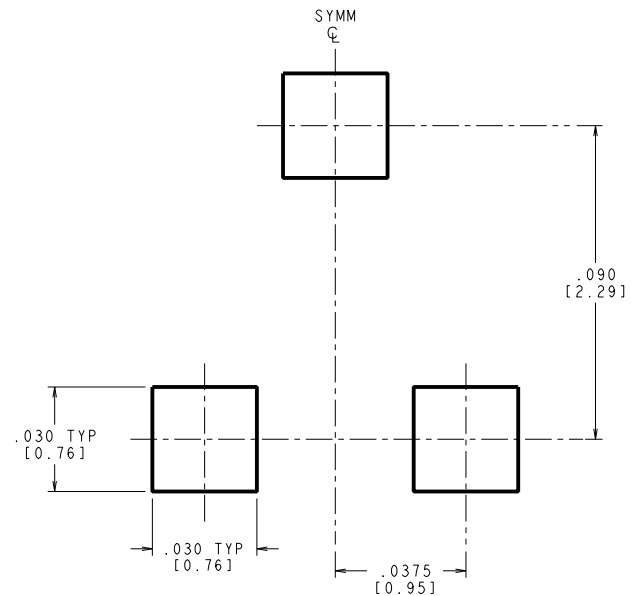
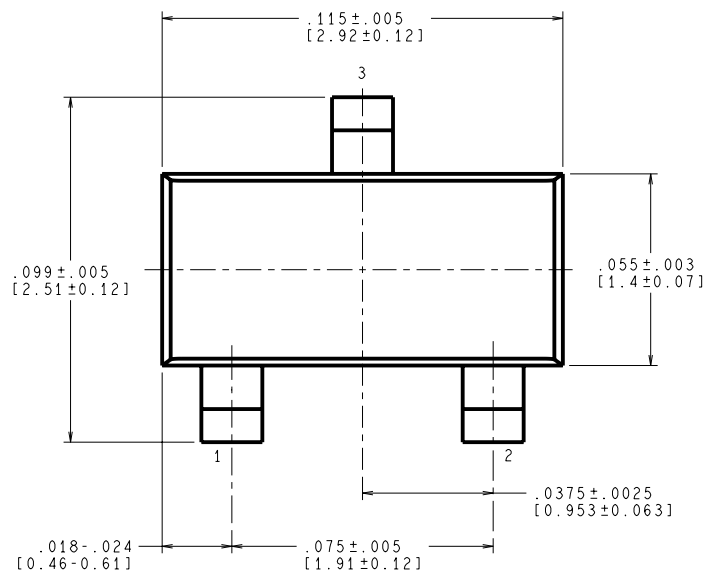
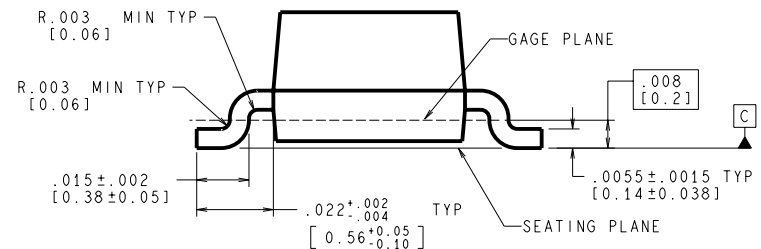
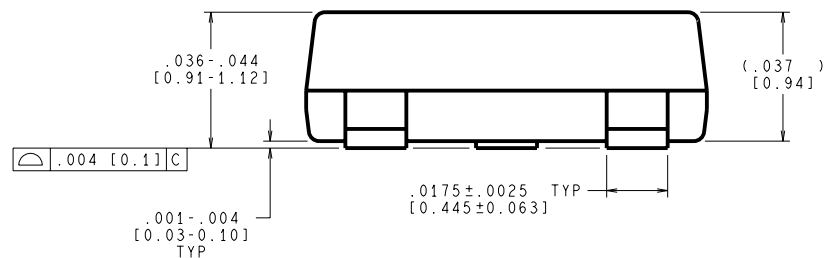


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11175	12/21/95	TL/OM
B	COPLANARITY .004[0.1] WAS .0015[0.038]; NOTE 1: 200 WAS 150, 5.08 WAS 3.81	11927	03/10/1998	MS/



LAND PATTERN RECOMMENDATION



**CONTROLLING DIMENSION IS INCH
VALUES IN () ARE MILLIMETERS**

NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH TO BE 200 MICROINCHES/ 5.08 MICROMETERS MINIMUM TIN/LEAD (SOLDER) ON COPPER.
2. NO JEDEC REGISTRATION AS OF MAR 1998.

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor dr., Santa Clara, CA 95052-8090									
DRAWN T. LEQUANG		12/21/95											
DTG. CHK.													
ENGR. CHK.													
				MOLDED PACKAGE, SUPER-SOT, 3 LEAD									
 PROJECTION				<table><tr><td>SCALE</td><td>SIZE</td><td>DRAWING NUMBER</td><td>REV</td></tr><tr><td>N/A</td><td>C</td><td>(SC)MKT-MA03B</td><td>B</td></tr></table>		SCALE	SIZE	DRAWING NUMBER	REV	N/A	C	(SC)MKT-MA03B	B
SCALE	SIZE	DRAWING NUMBER	REV										
N/A	C	(SC)MKT-MA03B	B										
INCH (MM)		DO NOT SCALE DRAWING		SHEET 1 of 1									